

FTS1001-VB Datasheet

Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
- 30	0.036 at $V_{GS} = -10$ V	- 5.2
	0.055 at $V_{GS} = -4.5$ V	- 4.2

FEATURES

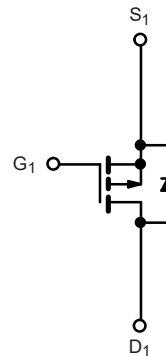
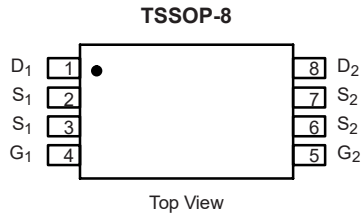
- Halogen-free
- Trench Power MOSFETs

APPLICATIONS

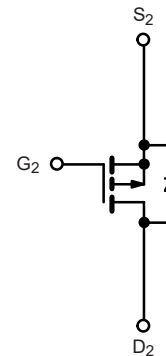
- Load Switch
- Battery Switch



RoHS
COMPLIANT



P-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted					
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	- 30		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	$T_A = 25^\circ\text{C}$	I_D	- 5.2	- 4.1	A
	$T_A = 70^\circ\text{C}$		- 4.2	- 3.6	
Pulsed Drain Current (10 μs Pulse Width)		I_{DM}	- 30		
Continuous Source Current (Diode Conduction) ^a		I_S	- 1.0	- 0.70	
Maximum Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	1.14	0.83	W
	$T_A = 70^\circ\text{C}$		0.73	0.53	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		$^\circ\text{C}$

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \leq 10$ s	R_{thJA}	86	110	$^\circ\text{C/W}$
	Steady State		124	150	
Maximum Junction-to-Foot	Steady State	R_{thJF}	52	65	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

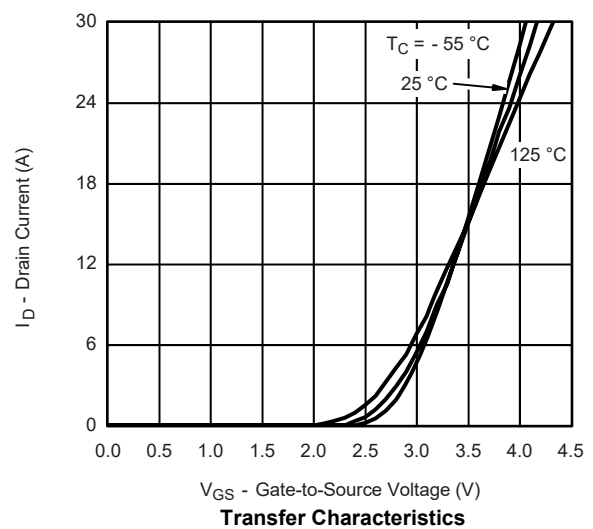
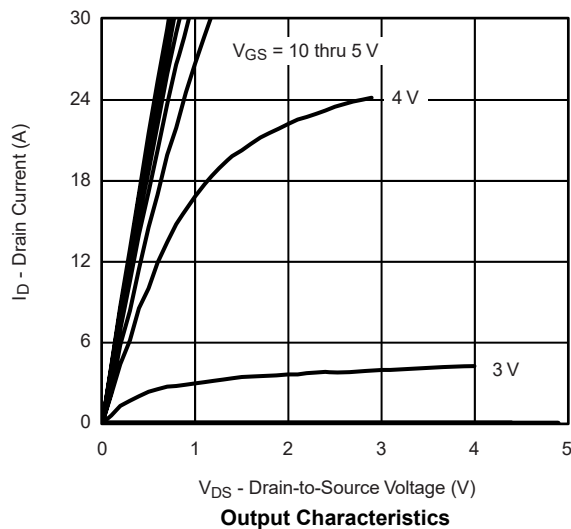
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$	-1.0		-3.0	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30\text{ V}$, $V_{GS} = 0\text{ V}$			-1	μA
		$V_{DS} = -30\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^{\circ}\text{C}$			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq -5\text{ V}$, $V_{GS} = -10\text{ V}$	-15			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$, $I_D = -4.7\text{ A}$		0.036		Ω
		$V_{GS} = -4.5\text{ V}$, $I_D = -3.8\text{ A}$		0.055		
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15\text{ V}$, $I_D = -4.7\text{ A}$		14		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -1.0\text{ A}$, $V_{GS} = 0\text{ V}$		-0.74	-1.1	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -15\text{ V}$, $V_{GS} = -4.5\text{ V}$, $I_D = -4.7\text{ A}$		13	20	nC
Gate-Source Charge	Q_{gs}			3		
Gate-Drain Charge	Q_{gd}			5.8		
Gate Resistance	R_g	$f = 1.0\text{ MHz}$		4.6		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -15\text{ V}$, $R_L = 15\text{ }\Omega$ $I_D \cong -1\text{ A}$, $V_{GEN} = -10\text{ V}$, $R_G = 6\text{ }\Omega$		13	20	ns
Rise Time	t_r			14	22	
Turn-Off Delay Time	$t_{d(off)}$			52	80	
Fall Time	t_f			26	40	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -1.0\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$		40	60	

Notes:

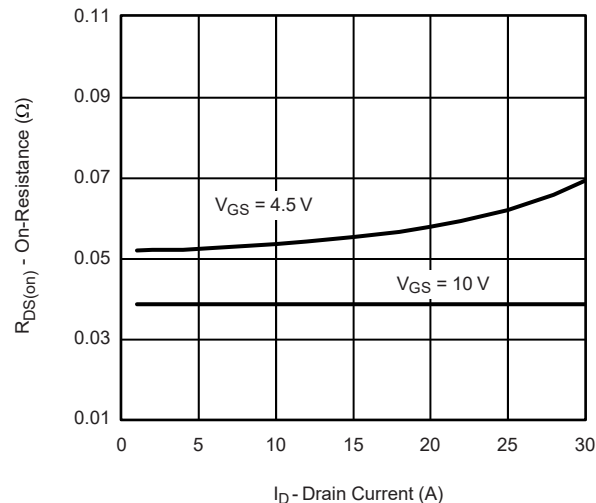
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

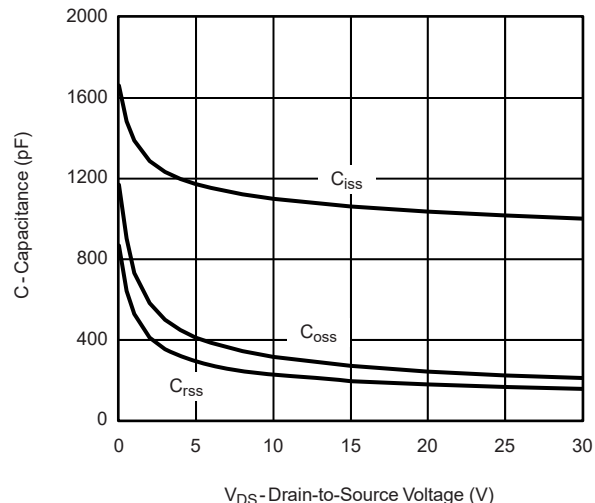
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $25\text{ }^{\circ}\text{C}$, unless otherwise noted

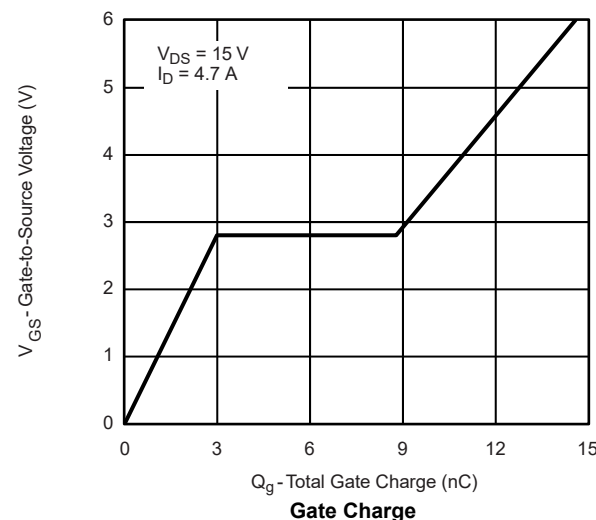
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



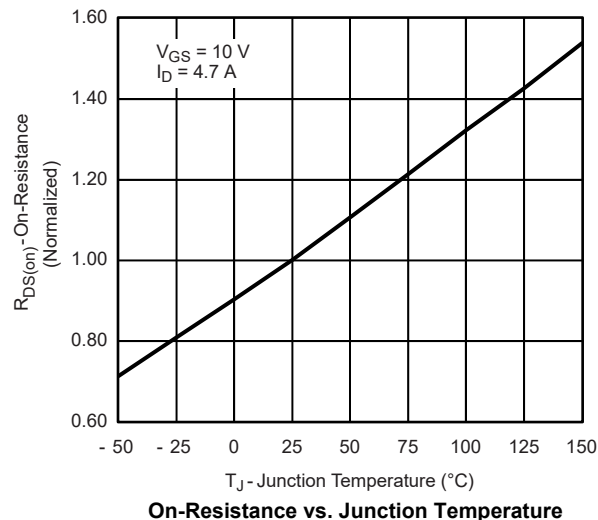
On-Resistance vs. Drain Current



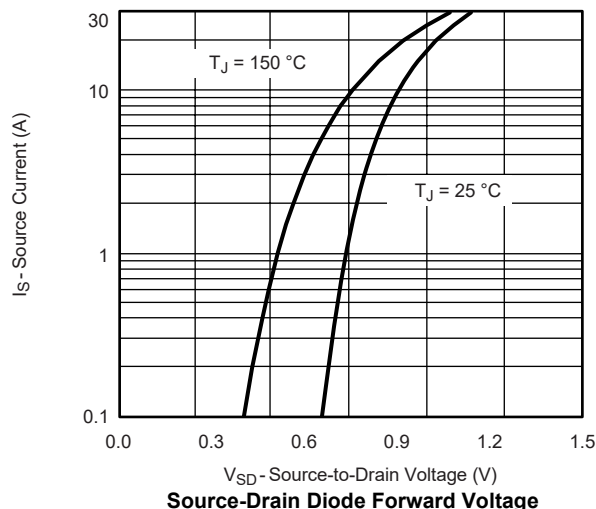
Capacitance



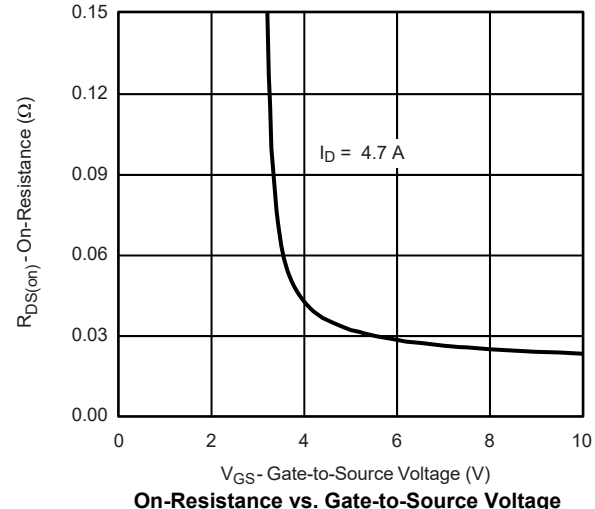
Gate Charge



On-Resistance vs. Junction Temperature

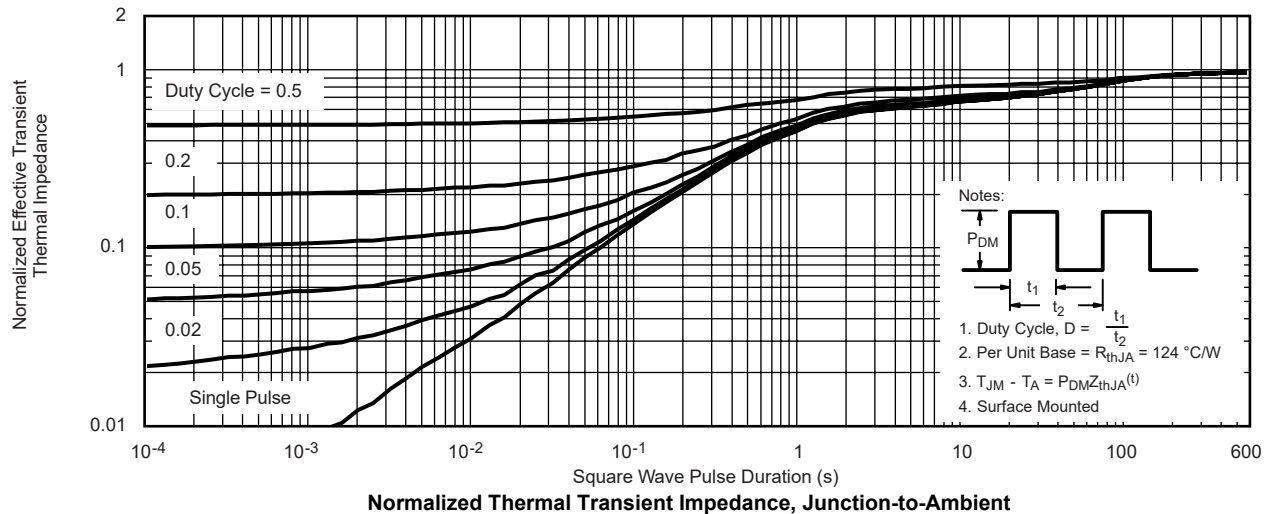
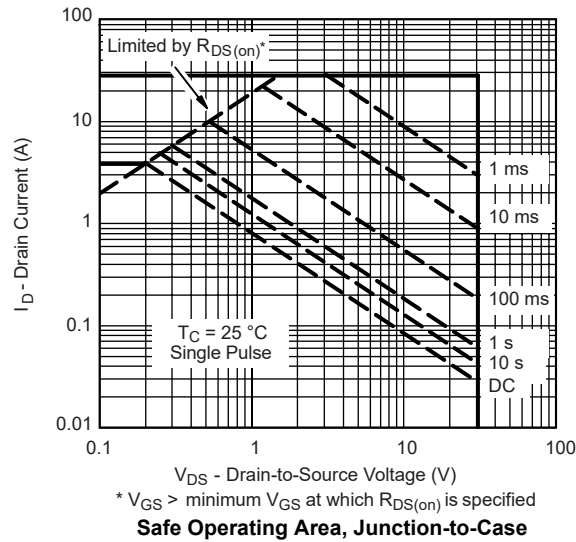
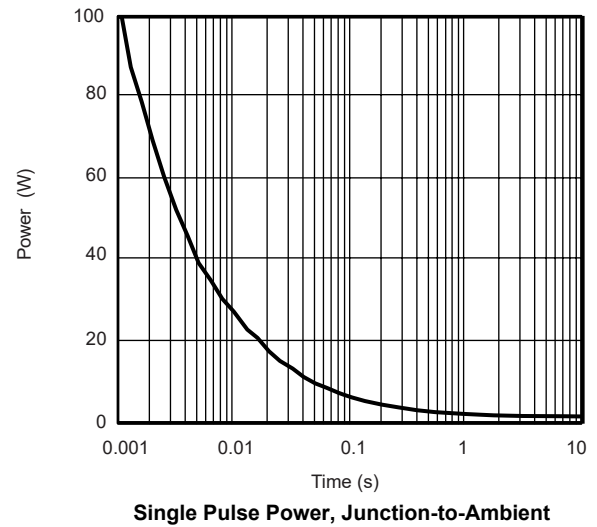
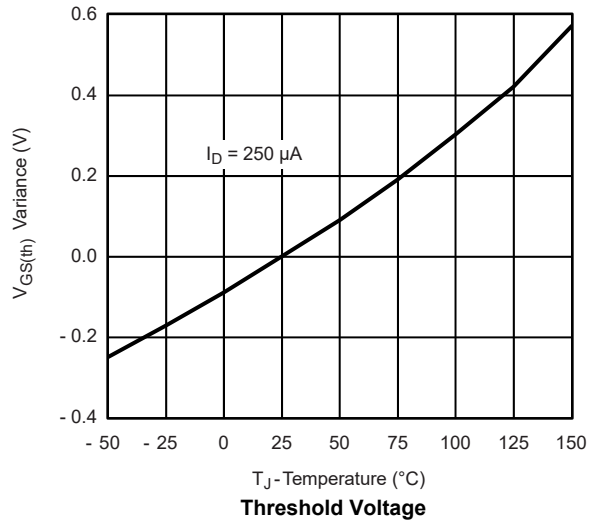


Source-Drain Diode Forward Voltage

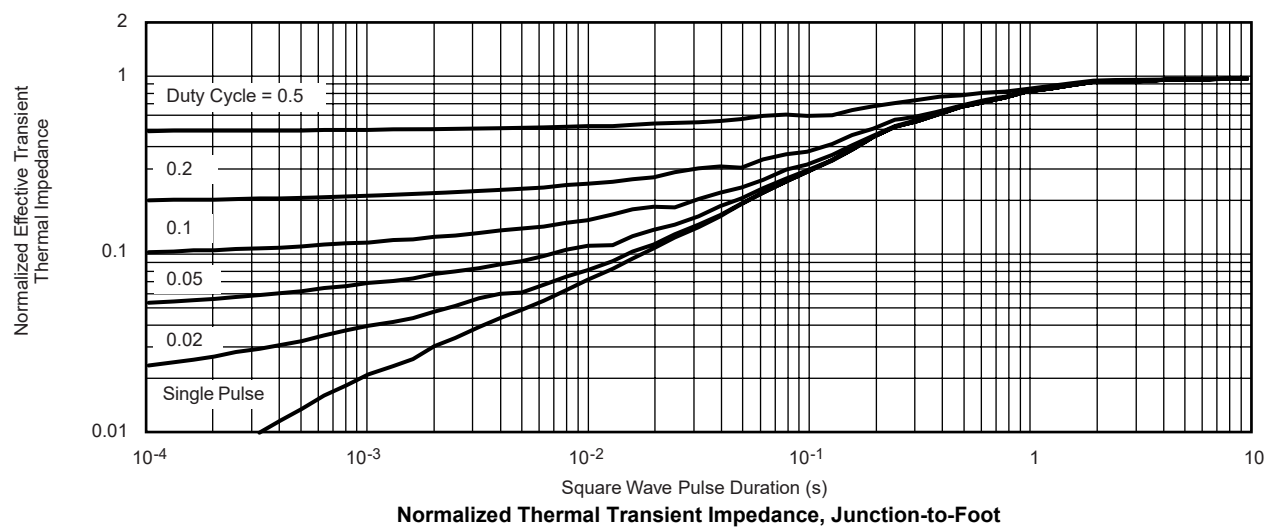


On-Resistance vs. Gate-to-Source Voltage

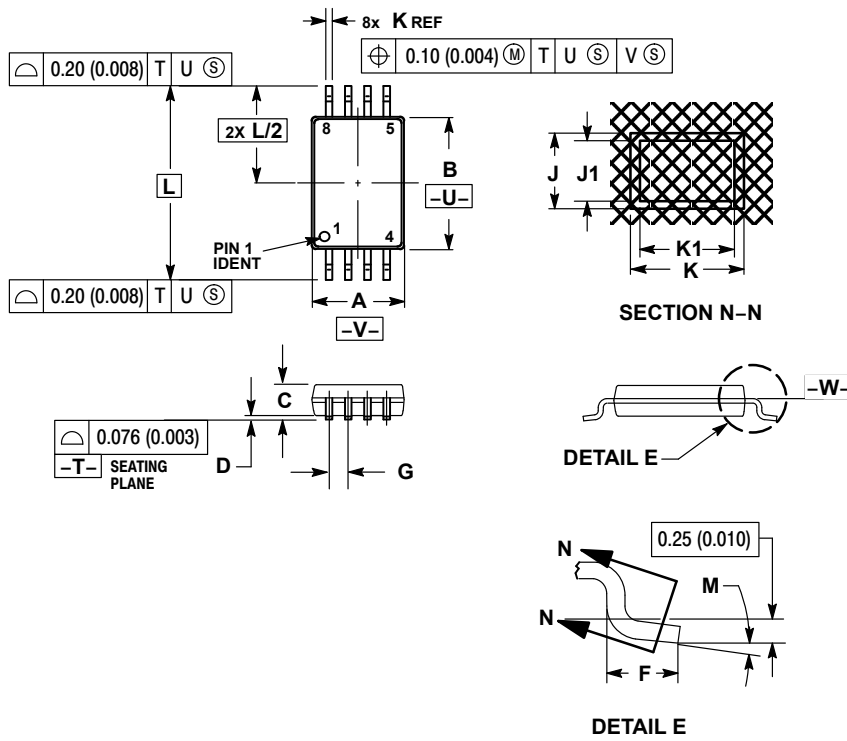
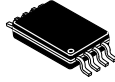
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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TSSOP-8



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0	8°

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